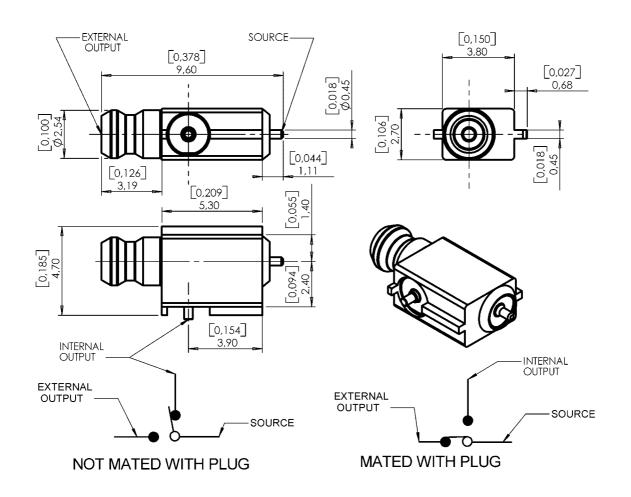
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Series: MOEBIUS





All dimensions are in mm/ [inch]



COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BRASS BRASS -PEEK - -NC	NPGR NPGR NPGR

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PACKAGING

Standard	Unit	Other
2800	-	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance	50 Ω
Frequency	0-6 GHz
VSWR (not mated)	1.2+0.05 x F(GHz) Max
VSWR (mated with plug)	1.05+0.05 x F(GHz) Maxi

*Insertion loss DC to 2 Ghz	0.15	dB Maxi
*Insertion loss 2 to 3 Ghz	0.2	dB Maxi
*Insertion loss 3 to 6 Ghz	0.5	dB Maxi
* not mated with PCB		

**Isolation loss DC to 1Ghz	30	dB min
**Isolation loss 1 to 3Ghz	20	dB min
**Isolation loss 3 to 6Ghz	20	dB min

** mated with plug

Voltage rating	100	Veff Maxi
Dielectric withstanding voltage	250	Veff mini
Insulation resistance	3000	$M\Omega$ mini

ENVIRONMENTAL

	Operating temperature Hermetic seal	-40/+110	° C Atm.cm3/s
Maxi	Panel leakage		

OTHER CHARACTERISTICS

Assembly instruction

Others:

Vibration no electrical discontinuity of 10 µs or more Condition test: 10 to 500 Hz, single amplitude of 1.5 mm, speed of 10 g, 2 hours in each of the 3 axis

MECHANICAL CHARACTERISTICS

Mating life **25000** Cycles Weight **0,38000.** g

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necessary.

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SOLDER PROCEDURE

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 microns mini (0.006 inch mini). Verify that the edges of the zone are clean.

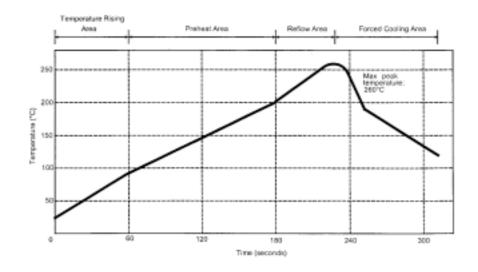
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.

- 3. Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE

INFORMATION ABOUT PAD



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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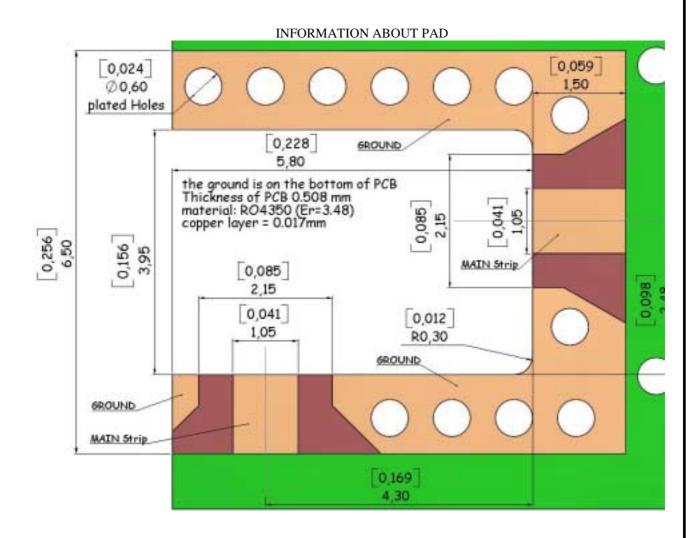
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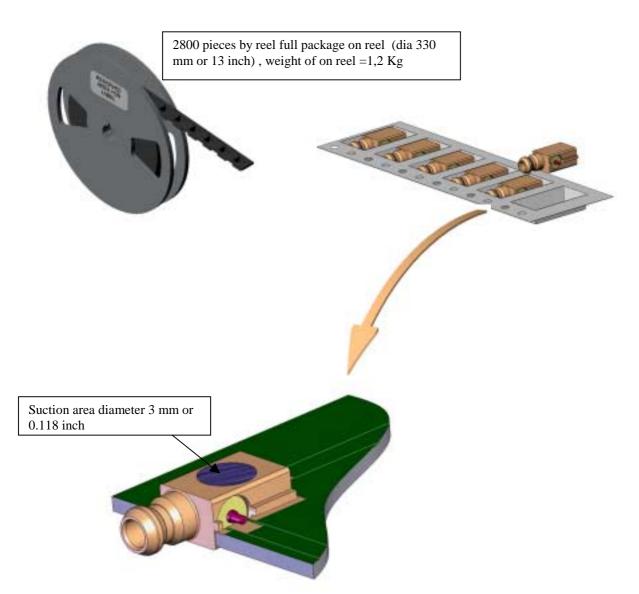


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